US00D597497S

(12) **United States Design Patent**
Chen et al.

(10) **Patent No.: US D597,497 S**
(45) **Date of Patent: ** Aug. 4, 2009**

(54) **HEAT DISSIPATING MODULE**

(75) Inventors: **Chin-Ming Chen**, Taoyuan Hsien (TW); **Yu-Hung Huang**, Taoyuan Hsien (TW); **Chun-Yang Hung**, Taoyuan Hsien (TW); **Sung-Ching Ho**, Taoyuan Hsien (TW)

(73) Assignee: **Delta Electronics Inc.**, Taoyuan Hsien (TW)

(**) Term: **14 Years**

(21) Appl. No.: **29/290,286**

(22) Filed: **Nov. 15, 2007**

(30) **Foreign Application Priority Data**

Oct. 26, 2007 (TW) 96305815

(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/179**
(58) **Field of Classification Search** D13/179; 165/80.3, 104.33, 151, 122, 185; 257/706, 257/707, 718–722; 361/687, 695, 697, 700, 361/702, 704, 709, 710, 711, 719
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D266,082 S	*	9/1982	Asanuma	D13/179
6,446,708 B1	*	9/2002	Lai	165/80.3
D467,559 S	*	12/2002	Lee	D13/179
6,607,028 B1	*	8/2003	Wang et al.	165/185
2006/0219392 A1	*	10/2006	Lin	165/104.33
2006/0225866 A1	*	10/2006	Chen	165/80.3

* cited by examiner

Primary Examiner—Selina Sikder
(74) *Attorney, Agent, or Firm*—Birch, Stewart, Kolasch & Birch, LLP

(57) **CLAIM**

The ornamental design for a heat dissipating module, as shown and described herein.

DESCRIPTION

FIG. **1** is a perspective view of a heat dissipating module showing our new design;

FIG. **2** is a front elevational view thereof;

FIG. **3** is a rear eleavational view thereof;

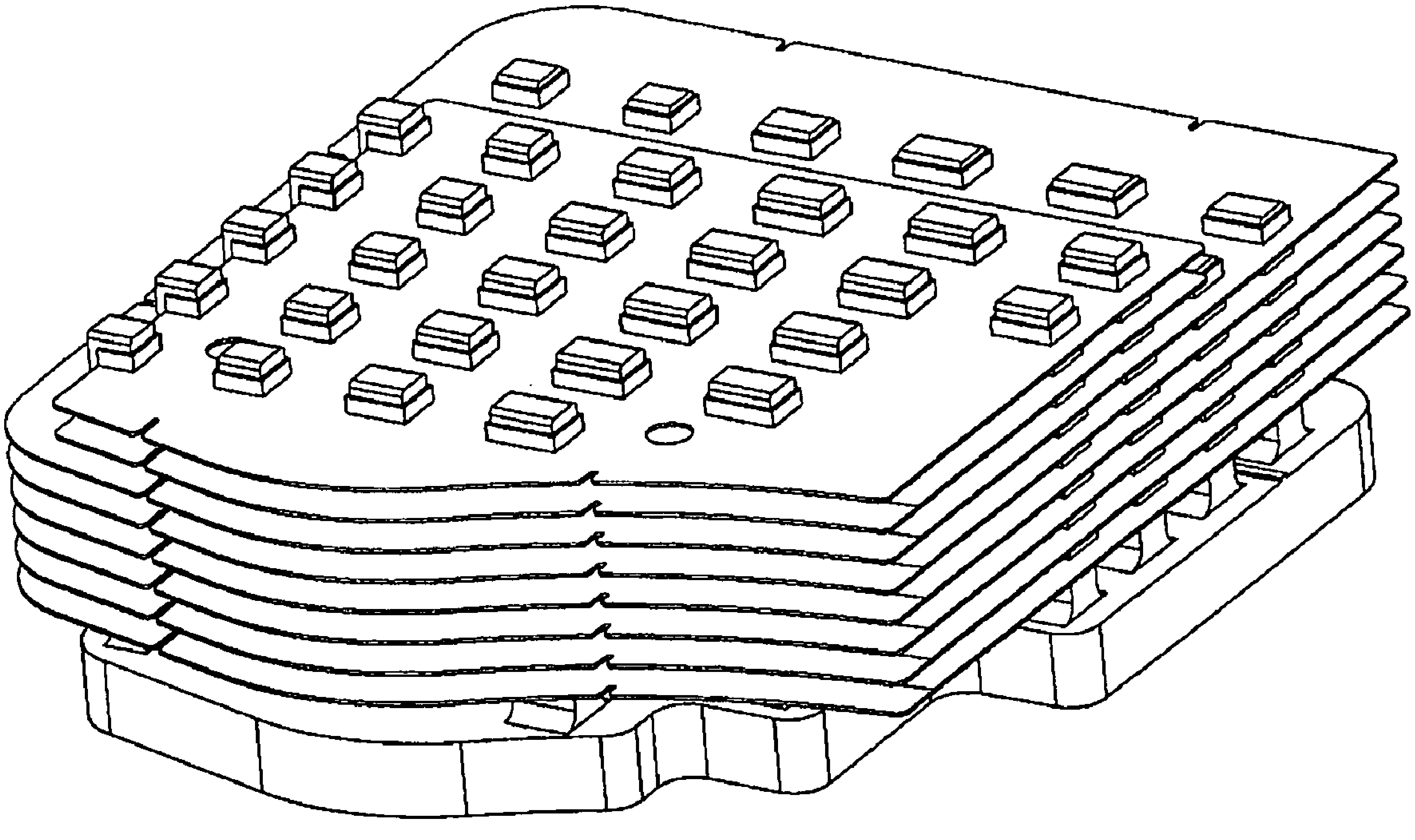
FIG. **4** is a left side elevational view thereof; and

FIG. **5** is a right side elevational view thereof.

FIG. **6** is a top plan view thereof; and,

FIG. **7** is a bottom plan view thereof.

1 Claim, 5 Drawing Sheets



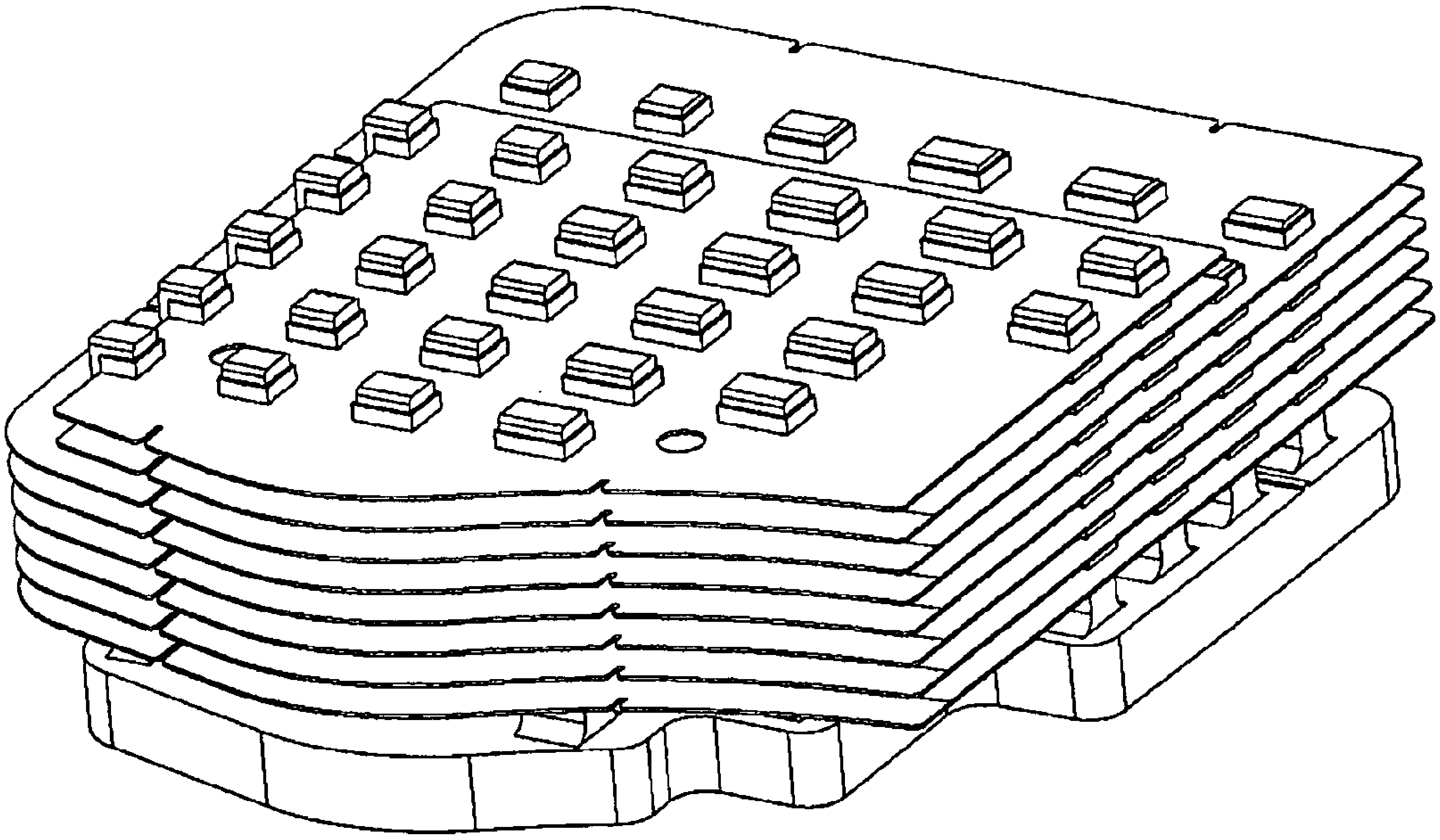


FIG. 1

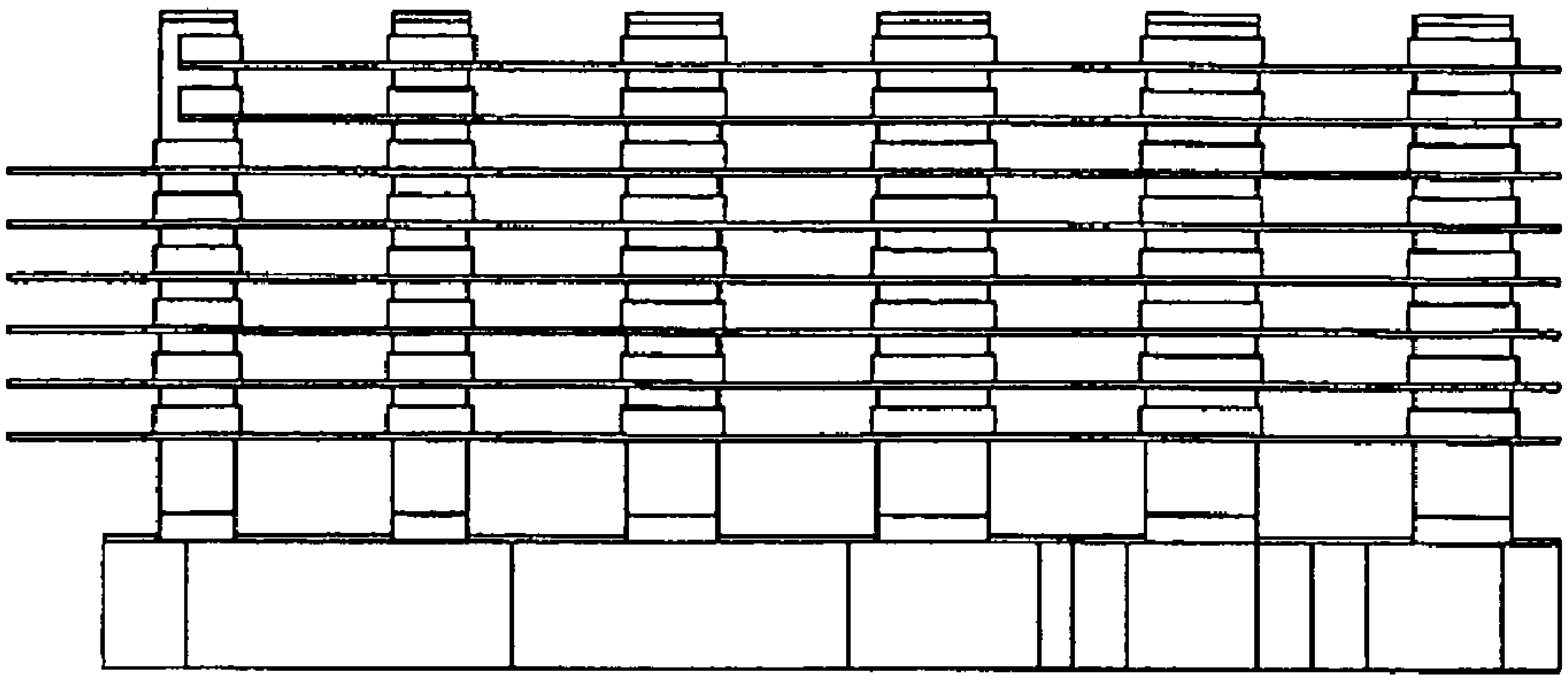


FIG. 2

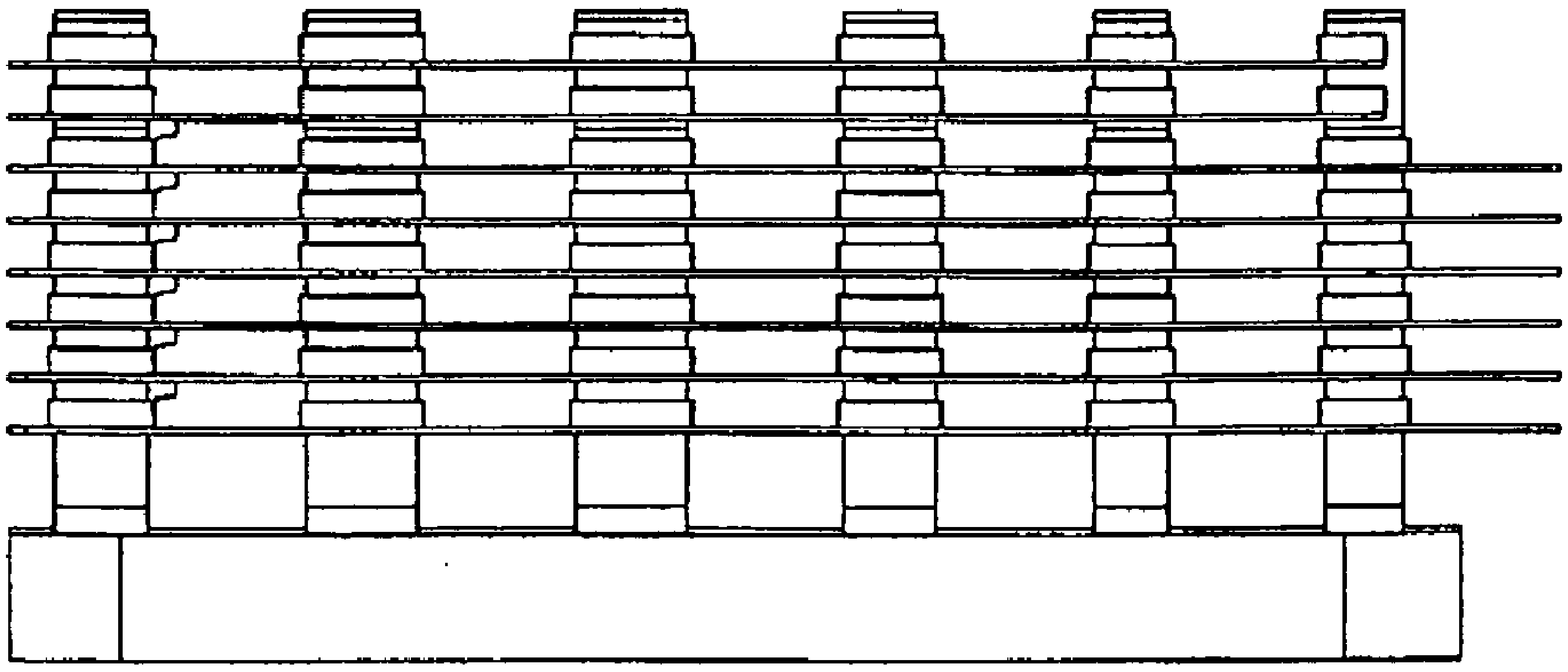


FIG. 3

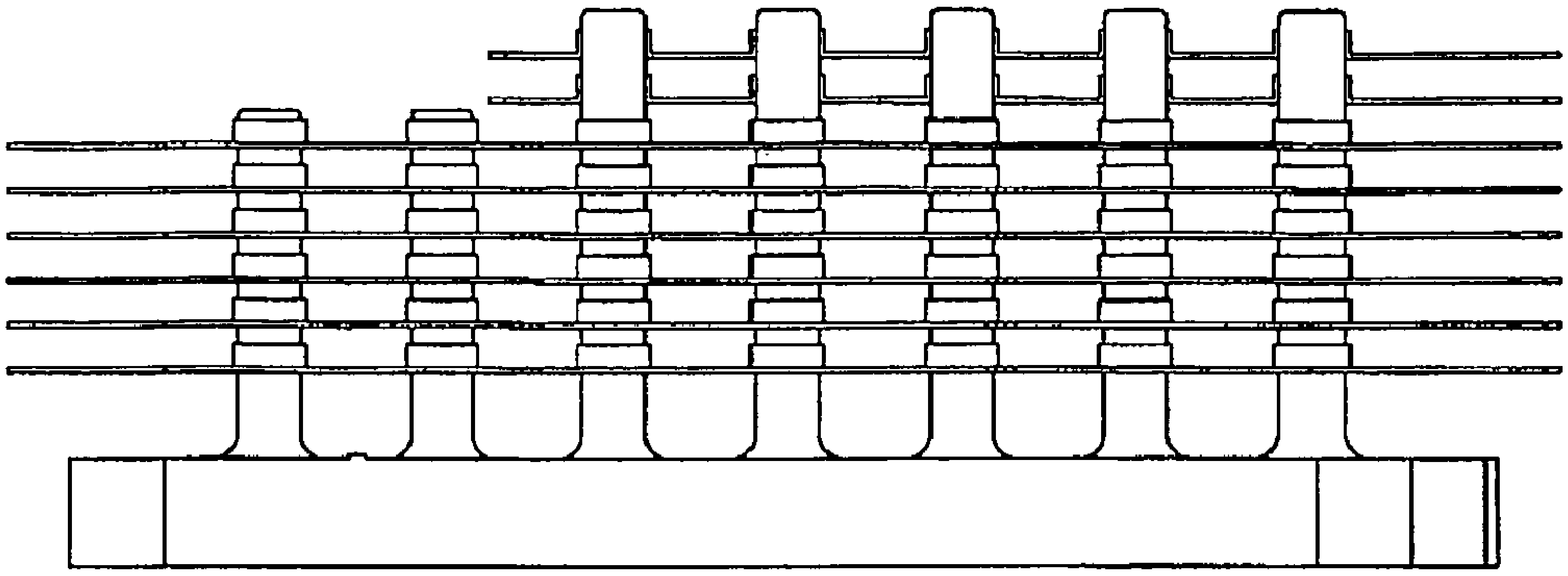


FIG. 4

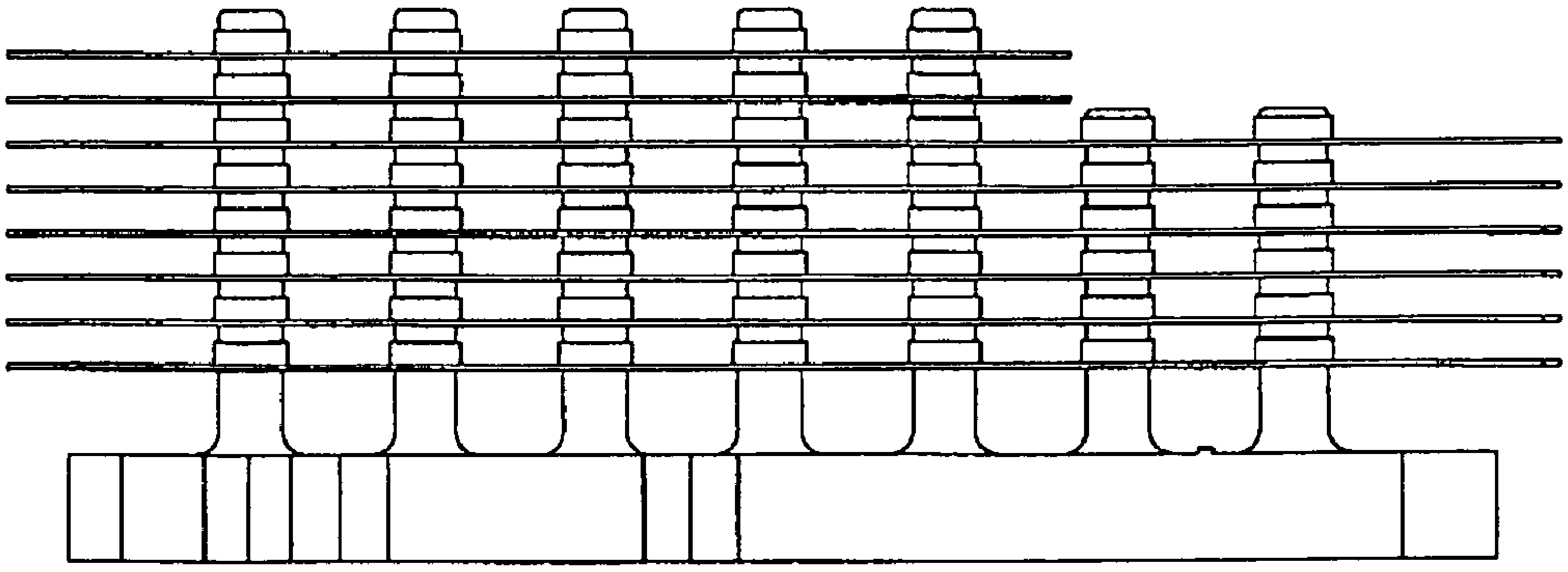


FIG. 5

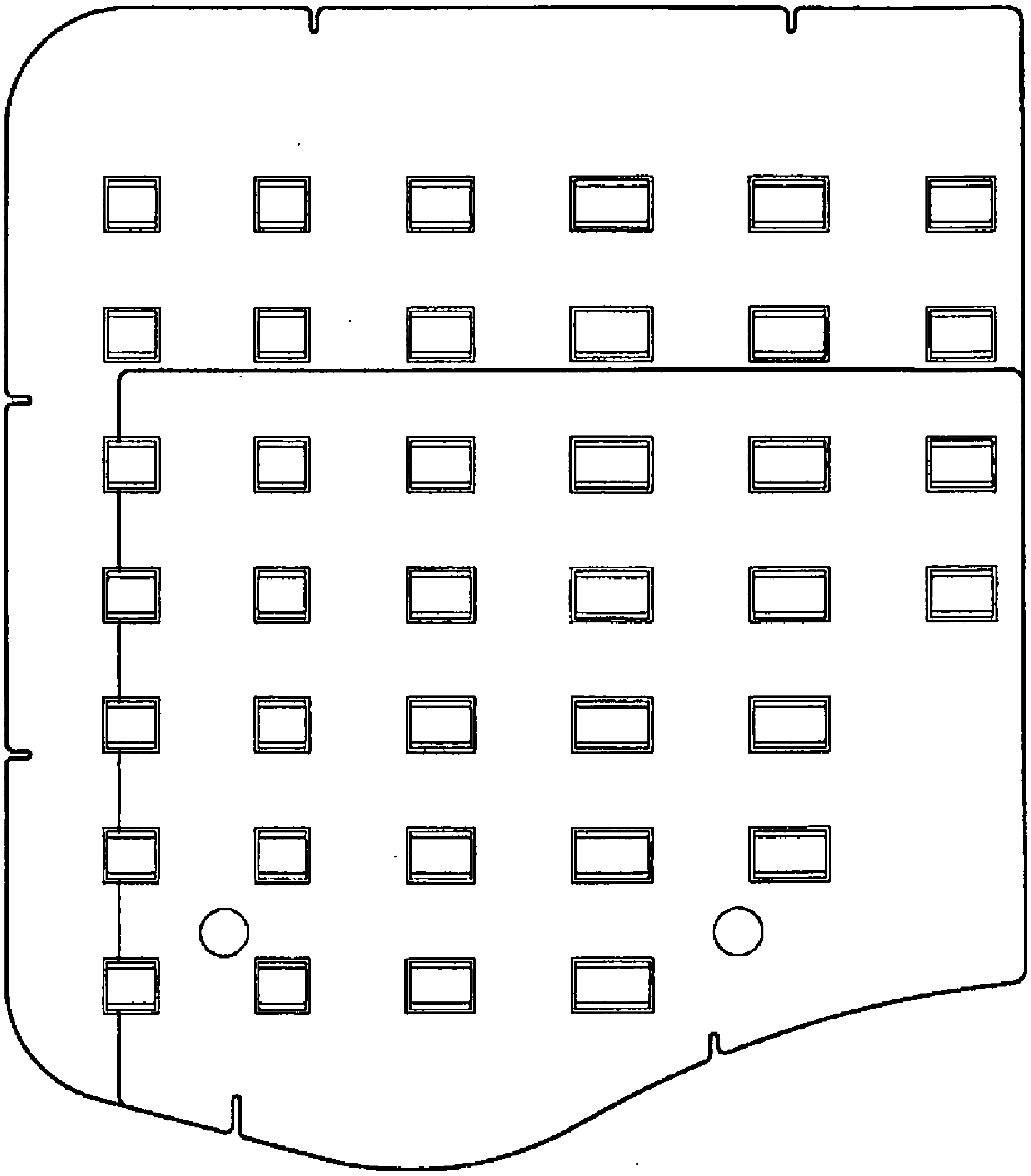


FIG. 6

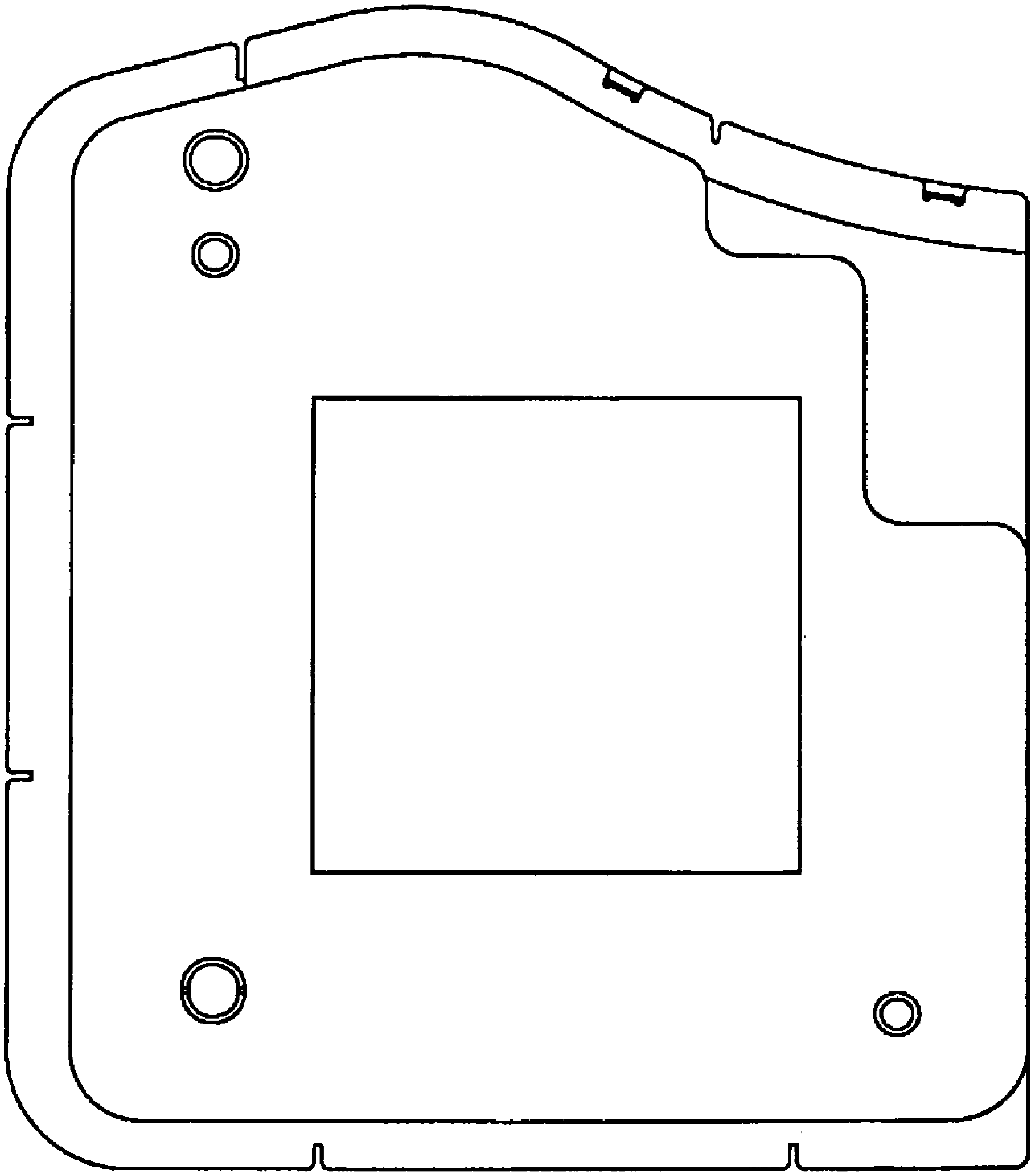


FIG. 7